



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In Re: Appn. Ser. No. <sup>09</sup>08/512,400

: Art Unit 1725

Filed 2/24/00

: Exr. J. Johnson

Inventors Gelorme et al

: Atty. Dkt.No.YO999-510

For: ELECTRICALLY CONDUCTING ADHESIVES FOR VIA FILL APPLICATIONS

Commissioner of Patents and Trademarks

Washington, D.C. 20231

Sir:

Provided herewith is a Response to the Office Action of 7/19/00 in the above identified application.

In the Claims

Cancel claims 1 - 8.

Kindly rewrite the combination of claims 9 and 11, including the change of preamble specified in the objection on page 2 of the office action of 7/19/00 as claim 14 as follows then cancel claims 9 and 11.

- 1 14. A method for manufacturing an electronic apparatus comprising the serial combination
- 2 of the steps of:
- 3 providing an adhesive paste,
- 4 said adhesive paste having random sizes of 5 -7 micrometer diameter range Cu particles
- 5 each coated BiSn suspended in a vehicle of a mixture of cyclo-aliphatic epoxy, phenoxy
- 6 polymer, and a flux in a proportion of epoxy 86%, phenoxy polymer 10%, and flux 4 %,